

CD40100BMS

CMOS 32-Stage Static Left/Right Shift Register

December 1992

Features

- High Voltage Type (20V Rating)
- Fully Static Operation
- · Shift Left/Shift Right Capability
- Multiple Package Cascading
- · Recirculate Capability
- . LIFO of FIFO Capability
- 100% Tested for Quiescent Current at 20V
- . 5V, 10V and 15V Parametric Ratings
- Maximum Input Current of 1μA at 18V Over Full Package Temperature Range; 100nA at 18V and +25°C
- Noise Margin (Over Full Package/Temperature Range)
 - 1V at VDD = 5V
 - 2V at VDD = 10V
 - 2.5V at VDD = 15V
- Standardized, Symmetrical Output Characteristics
- Meets All Requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"

Applications

Pinout

- · Serial Shift Registers
- Time Delay Circuits
- Expandable N-Bit Data Storage Stack (LIFO Operation)

Description

CD40100BMS is a 32-Stage shift register containing 32 D-type master-slave flip-flops.

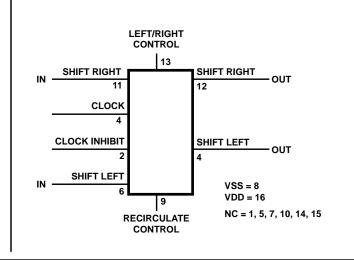
The data present at the SHIFT RIGHT INPUT is transferred into the first register stage synchronously with the positive CLOCK edge, provided the LEFT/RIGHT CONTROL is at a low level, the RECIRCULATE CONTROL is at a high level, and the CLOCK INHIBIT is low. If the LEFT/RIGHT CONTROL is at a high level and the RECIRCULATE CONTROL is also high, data at the SHIFT LEFT INPUT is transferred into the 32nd register stage synchronously with the positive CLOCK transition, provided the CLOCK INHIBIT is low. The state of the LEFT/RIGHT CONTROL, RECIRCULATE CONTROL, and CLOCK INHIBIT should not be changed when the CLOCK is high.

Data is shifted one stage left or one stage right depending on the state of the LEFT/RIGHT CONTROL, synchronously with the positive CLOCK edge. Data clocked into the first or 32nd register states is available at the SHIFT LEFT or SHIFT RIGHT OUTPUT respectively, on the next negative CLOCK transition (see Data Transfer Table). No shifting occurs on the positive CLOCK edge if the CLOCK INHIBIT line is at a high level. With the RECIRCULATE CONTROL low, data in the 32nd stage is shifted into the first stage when the LEFT/RIGHT CONTROL is low, and from the first state to the 32nd stage when the LEFT/RIGHT CONTROL is low, and from the first state to the 32nd stage when the LEFT/RIGHT control is high. The CD40100BMS is supplied in these 16-lead outline packages:

Braze Seal DIP H4T
Frit Seal DIP H2R
Ceramic Flatpack H6W

Functional Diagram

CD40100BMS TOP VIEW 16 VDD NC 1 CLOCK INHIBIT 2 15 NC 14 NC CLOCK 3 LEFT/RIGHT SHIFT LEFT OUT 4 13 CONTROL NC 5 SHIFT RIGHT OUT SHIFT LEFT IN 6 SHIFT RIGHT IN NC RECIRCULATE vss CONTROL



NC = NO CONNECTION

Absolute Maximum Ratings

DC Supply Voltage Range, (VDD) -0.5V to +20V (Voltage Referenced to VSS Terminals) Input Voltage Range, All Inputs -0.5V to VDD +0.5V DC Input Current, Any One Input±10mA Operating Temperature Range -55°C to +125°C Package Types D, F, K, H Storage Temperature Range (TSTG) -65°C to +150°C Lead Temperature (During Soldering) +265°C At Distance 1/16 \pm 1/32 Inch (1.59mm \pm 0.79mm) from case for 10s Maximum

Reliability Information

Thermal Resistance	θ_{ja}	$\theta_{\sf jc}$
Ceramic DIP and FRIT Package	80°C/W	20°C/W
Flatpack Package	70°C/W	20°C/W
Maximum Package Power Dissipation (PD) at +125°C	
For T _A = -55°C to +100°C (Package Typ	e D, F, K)	500mW
For $T_A = +100^{\circ}$ C to $+125^{\circ}$ C (Package T		
		C to 200mW
Device Dissipation per Output Transistor .		100mW
For T _A = Full Package Temperature Ran		
Junction Temperature		+175°C

TABLE 1. DC ELECTRICAL PERFORMANCE CHARACTERISTICS

			GROUP A		LIM	IITS	
SYMBOL	CONDITIONS (1	NOTE 1)		TEMPERATURE	MIN	MAX	UNITS
IDD	VDD = 20V, VIN = VD	D or GND	1	+25°C	-	10	μΑ
			2	+125°C	-	1000	μΑ
	VDD = 18V, VIN = VD	D or GND	3	-55°C	-	10	μΑ
IIL	VIN = VDD or GND	VDD = 20	1	+25°C	-100	-	nA
			2	+125°C	-1000	-	nA
		VDD = 18V	3	-55°C	-100	-	nA
IIH	VIN = VDD or GND	VDD = 20	1	+25°C	-	100	nA
			2	+125°C	-	1000	nA
		VDD = 18V	3	-55°C	-	100	nA
VOL15	VDD = 15V, No Load	•	1, 2, 3	+25°C, +125°C, -55°C	-	50	mV
VOH15	VDD = 15V, No Load	(Note 3)	1, 2, 3	+25°C, +125°C, -55°C	14.95	-	V
IOL5	VDD = 5V, VOUT = 0.4V		1	+25°C	0.53	-	mA
IOL10	VDD = 10V, VOUT = 0.5V		1	+25°C	1.4	-	mA
IOL15	VDD = 15V, VOUT = 1	VDD = 15V, VOUT = 1.5V		+25°C	3.5	-	mA
IOH5A	VDD = 5V, VOUT = 4.6V		1	+25°C	-	-0.53	mA
IOH5B	VDD = 5V, VOUT = 2.	5V	1	+25°C	-	-1.8	mA
IOH10	VDD = 10V, VOUT = 9	9.5V	1	+25°C	-	-1.4	mA
IOH15	VDD = 15V, VOUT = 1	13.5V	1	+25°C	-	-3.5	mA
VNTH	VDD = 10V, ISS = -10	μΑ	1	+25°C	-2.8	-0.7	V
VPTH	VSS = 0V, IDD = 10μΑ	4	1	+25°C	0.7	2.8	V
F	VDD = 2.8V, VIN = VD	DD or GND	7	+25°C	VOH>	VOL <	V
	VDD = 20V, VIN = VD	D or GND	7	+25°C	VDD/2	VDD/2	
	VDD = 18V, VIN = VD	D or GND	8A	+125°C			
	VDD = 3V, VIN = VDD	or GND	8B	-55°C			
VIL	VDD = 5V, VOH > 4.5V, VOL < 0.5V		1, 2, 3	+25°C, +125°C, -55°C	-	1.5	V
VIH	VDD = 5V, VOH > 4.5V, VOL < 0.5V		1, 2, 3	+25°C, +125°C, -55°C	3.5	-	V
VIL	VDD = 15V, VOH > 13 VOL < 1.5V	VDD = 15V, VOH > 13.5V, VOL < 1.5V		+25°C, +125°C, -55°C	-	4	V
VIH	VDD = 15V, VOH > 13 VOL < 1.5V	3.5V,	1, 2, 3	+25°C, +125°C, -55°C	11	-	V
	IIL IIH VOL15 VOH15 IOL5 IOL10 IOL15 IOH5A IOH5B IOH10 IOH15 VNTH VPTH F VIL VIH VIL	IDD	IDD	IDD	SYMBOL CONDITIONS (NOTE 1) SUBGROUPS TEMPERATURE IDD VDD = 20V, VIN = VDD or GND 1 +25°C 2 +125°C 2 +125°C VDD = 18V, VIN = VDD or GND 3 -55°C IIIL VIN = VDD or GND VDD = 20 1 +25°C 2 +125°C 2 +125°C VDD = 18V 3 -55°C VDD = 18V 3 -55°C VDL15 VDD = 15V, No Load 1, 2, 3 +25°C, +125°C, -55°C VOH15 VDD = 15V, No Load (Note 3) 1, 2, 3 +25°C, +125°C, -55°C VOH15 VDD = 15V, No Load (Note 3) 1, 2, 3 +25°C, +125°C, -55°C VOH15 VDD = 15V, NO Load (Note 3) 1, 2, 3 +25°C, +125°C, -55°C VDD = 15V, VOUT = 0.5V 1 +25°C +25°C IOL15 VDD = 15V, VOUT = 0.5V 1 +25°C IOH5A VDD = 5V, VOUT = 2.5V 1 +25°C IOH5B VDD = 5V, VOUT = 9.5V 1 +25°C VOH1 <	SYMBOL CONDITIONS (NOTE 1) SUBGROUPS TEMPERATURE MIN	SYMBOL CONDITIONS (NOTE 1) SUBGROUPS TEMPERATURE MIN MAX

NOTES: 1. All voltages referenced to device GND, 100% testing being 3. For accuracy, voltage is measured differentially to VDD. Limit implemented.

2. Go/No Go test with limits applied to inputs.

is 0.050V max.

TABLE 2. AC ELECTRICAL PERFORMANCE CHARACTERISTICS

			GROUP A		LIM	ITS	
PARAMETER	SYMBOL	CONDITIONS (NOTE 1, 2)	SUBGROUPS	TEMPERATURE	MIN	MAX	UNITS
Propagation Delay	TPHL	VDD = 5V, VIN = VDD or GND	9	+25°C	-	720	ns
Clock to Shift Left/Right Output	TPLH		10, 11	+125°C, -55°C	-	972	ns
Transition Time	TTHL	VDD = 5V, VIN = VDD or GND	9	+25°C	-	200	ns
	TTLH		10, 11	+125°C, -55°C	-	270	ns
Maximum Clock Input	FCL	VDD = 5V, VIN = VDD or GND	9	+25°C	1	-	MHz
Frequency			10, 11	+125°C, -55°C	.74	-	MHz

NOTES:

- 1. VDD = 5V, CL = 50pF, RL = 200K
- 2. -55°C and $+125^{\circ}\text{C}$ limits guaranteed, 100% testing being implemented.

TABLE 3. ELECTRICAL PERFORMANCE CHARACTERISTICS

					LIMITS		
PARAMETER	SYMBOL	CONDITIONS	NOTES	TEMPERATURE	MIN	MAX UNI	
Supply Current	IDD	VDD = 5V, VIN = VDD or GND	1, 2	-55°C, +25°C	-	5	μΑ
				+125°C	-	150	μΑ
		VDD = 10V, VIN = VDD or GND	1, 2	-55°C, +25°C	-	10	μΑ
				+125°C	-	300	μА
		VDD = 15V, VIN = VDD or GND	1, 2	-55°C, +25°C	-	10	μА
				+125°C	-	600	μА
Output Voltage	VOL	VDD = 5V, No Load	1, 2	+25°C, +125°C, -55°C	-	50	mV
Output Voltage	VOL	VDD = 10V, No Load	1, 2	+25°C, +125°C, -55°C	-	50	mV
Output Voltage	VOH	VDD = 5V, No Load	1, 2	+25°C, +125°C, -55°C	4.95	-	V
Output Voltage	VOH	VDD = 10V, No Load	1, 2	+25°C, +125°C, -55°C	9.95	-	V
Output Current (Sink)	IOL5	VDD = 5V, VOUT = 0.4V	1, 2	+125°C	0.36	-	mA
				-55°C	0.64	-	mA
Output Current (Sink)	IOL10	/DD = 10V, VOUT = 0.5V 1, 2	1, 2	+125°C	0.9	-	mA
				-55°C	1.6	-	mA
Output Current (Sink)	IOL15	VDD = 15V, VOUT = 1.5V	1, 2	+125°C	2.4	-	mA
				-55°C	4.2	-	mA
Output Current (Source)	IOH5A	VDD = 5V, VOUT = 4.6V	1, 2	+125°C	-	-0.36	mA
				-55°C	-	-0.64	mA
Output Current (Source)	IOH5B	VDD = 5V, VOUT = 2.5V	1, 2	+125°C	-	-1.15	mA
				-55°C	-	-2.0	mA
Output Current (Source)	IOH10	VDD = 10V, VOUT = 9.5V	1, 2	+125°C	-	-0.9	mA
				-55°C	-	-1.6	mA
Output Current (Source)	IOH15	VDD =15V, VOUT = 13.5V	1, 2	+125°C	-	-2.4	mA
				-55°C	-	-4.2	mA

TABLE 3. ELECTRICAL PERFORMANCE CHARACTERISTICS (Continued)

					LIN	IITS	
PARAMETER	SYMBOL	CONDITIONS	NOTES	TEMPERATURE	MIN	MAX	UNITS
Input Voltage Low	VIL	VDD = 10V, VOH > 9V, VOL < 1V	1, 2	+25°C, +125°C, -55°C	-	3	V
Input Voltage High	VIH	VDD = 10V, VOH > 9V, VOL < 1V	1, 2	+25°C, +125°C, -55°C	+7	-	V
Propagation Delay	TPHL1	VDD = 10V	1, 2, 3	+25°C	-	330	ns
Clock to Shift Left/Right Output	TPLH1	VDD = 15V	1, 2, 3	+25°C	=	230	ns
Transition Time	TTHL	VDD = 10V	1, 2, 3	+25°C	-	100	ns
		VDD = 15V	1, 2, 3	+25°C	-	80	ns
Maximum Clock Input	FCL	VDD = 10V	1, 2, 3	+25°C	2.5	-	MHz
Frequency		VDD = 15V	1, 2, 3	+25°C	3	-	MHz
Minimum Data Setup	TS	VDD = 5V	1, 2, 3	+25°C	-	100	ns
Time		VDD = 10V	1, 2, 3	+25°C	-	20	ns
		VDD = 15V	1, 2, 3	+25°C	-	10	ns
Minimum Data Hold Time	TH	VDD = 5V	1, 2, 3	+25°C	-	275	ns
		VDD = 10V	1, 2, 3	+25°C	-	100	ns
		VDD = 15V	1, 2, 3	+25°C	-	75	ns
Minimum Clock Pulse	TWL	VDD = 5V	1, 2, 3	+25°C	-	450	ns
Width Low Level		VDD = 10V	1, 2, 3	+25°C	-	230	ns
		VDD = 15V	1, 2, 3	+25°C	-	190	ns
Minimum Clock Pulse	TWH	VDD = 5V	1, 2, 3	+25°C	-	280	ns
Width High Level		VDD = 10V	1, 2, 3	+25°C	-	150	ns
		VDD = 15V	1, 2, 3	+25°C	-	140	ns
Input Capacitance	CIN	Any Input	1, 2	+25°C	-	7.5	pF

NOTES:

- 1. All voltages referenced to device GND.
- 2. The parameters listed on Table 3 are controlled via design or process and are not directly tested. These parameters are characterized on initial design release and upon design changes which would affect these characteristics.
- 3. CL = 50pF, RL = 200K, Input TR, TF < 20ns.

TABLE 4. POST IRRADIATION ELECTRICAL PERFORMANCE CHARACTERISTICS

					LIM	IITS	
PARAMETER	SYMBOL	CONDITIONS	NOTES	TEMPERATURE	MIN	MAX	UNITS
Supply Current	IDD	VDD = 20V, VIN = VDD or GND	1, 4	+25°C	-	25	μΑ
N Threshold Voltage	VNTH	VDD = 10V, ISS = -10μA	1, 4	+25°C	-2.8	-0.2	V
N Threshold Voltage Delta	ΔVTN	VDD = 10V, ISS = -10μA	1, 4	+25°C	-	±1	V
P Threshold Voltage	VTP	VSS = 0V, IDD = 10μA	1, 4	+25°C	0.2	2.8	V
P Threshold Voltage Delta	ΔVΤΡ	VSS = 0V, IDD = 10μA	1, 4	+25°C	-	±1	V
Functional	F	VDD = 18V, VIN = VDD or GND VDD = 3V, VIN = VDD or GND	1	+25°C	VOH > VDD/2	VOL < VDD/2	V

TABLE 4. POST IRRADIATION ELECTRICAL PERFORMANCE CHARACTERISTICS

					LIMITS		
PARAMETER	SYMBOL	CONDITIONS	NOTES	TEMPERATURE	MIN	MAX	UNITS
Propagation Delay Time	TPHL TPLH	VDD = 5V	1, 2, 3, 4	+25°C	-	1.35 x +25°C Limit	ns

NOTES: 1. All voltages referenced to device GND.

3. See Table 2 for +25°C limit.

2. CL = 50pF, RL = 200K, Input TR, TF < 20ns.

4. Read and Record

TABLE 5. BURN-IN AND LIFE TEST DELTA PARAMETERS +25°C

PARAMETER	SYMBOL	DELTA LIMIT
Supply Current - MSI-2	IDD	± 1.0μA
Output Current (Sink)	IOL5	± 20% x Pre-Test Reading
Output Current (Source)	IOH5A	± 20% x Pre-Test Reading
ON Resistance	RONDEL10	± 20% x Pre-Test Reading

TABLE 6. APPLICABLE SUBGROUPS

CONFORMANCE GROUP		MIL-STD-883 METHOD	GROUP A SUBGROUPS	READ AND RECORD
Initial Test (Pre Burn-In)		100% 5004	1, 7, 9	IDD, IOL5, IOH5A
Interim Test	1 (Post Burn-In)	100% 5004	1, 7, 9	IDD, IOL5, IOH5A
Interim Test	2 (Post Burn-In)	100% 5004	1, 7, 9	IDD, IOL5, IOH5A
PDA (Note 1)		100% 5004	1, 7, 9, Deltas	
Interim Test 3 (Post Burn-In)		100% 5004	1, 7, 9	IDD, IOL5, IOH5A
PDA (Note	e 1)	100% 5004	1, 7, 9, Deltas	
Final Test		100% 5004	2, 3, 8A, 8B, 10, 11	
Group A		Sample 5005	1, 2, 3, 7, 8A, 8B, 9, 10, 11	
Group B Subgroup B-5		Sample 5005	1, 2, 3, 7, 8A, 8B, 9, 10, 11, Deltas	Subgroups 1, 2, 3, 9, 10, 11
Subgroup B-6		Sample 5005	1, 7, 9	
Group D	Group D		1, 2, 3, 8A, 8B, 9	Subgroups 1, 2 3

NOTE: 1.5% Parameteric, 3% Functional; Cumulative for Static 1 and 2.

TABLE 7. TOTAL DOSE IRRADIATION

	MIL-STD-883	TE	ST	READ AND	RECORD
CONFORMANCE GROUPS	METHOD	PRE-IRRAD POST-IRRAD		PRE-IRRAD	POST-IRRAD
Group E Subgroup 2	5005	1, 7, 9	Table 4	1, 9	Table 4

TABLE 8. BURN-IN AND IRRADIATION TEST CONNECTIONS

					OSCILLATOR	
FUNCTION	OPEN	GROUND	VDD	9V \pm -0.5V	50kHz	25kHz
Static Burn-In 1 Note 1	1, 4, 5, 7, 10, 12, 14, 15	2, 3, 6, 8, 9, 11, 13	16			
Static Burn-In 2 Note 1	1, 4, 5, 7, 10, 12, 14, 15	8	2, 3, 6, 9, 11, 13, 16			
Dynamic Burn- In Note 1	1, 5, 7, 10, 14, 15	2, 8, 13	9, 16	4, 12	3	6, 11
Irradiation Note 2	1, 4, 5, 7, 10, 12, 14, 15	8	2, 3, 6, 9, 11, 13, 16			

TABLE 8. BURN-IN AND IRRADIATION TEST CONNECTIONS (Continued)

					OSCILLATOR	
FUNCTION	OPEN	GROUND	VDD	9V \pm -0.5V	50kHz	25kHz

NOTES:

- 1. Each pin except VDD and GND will have a series resistor of 10K \pm 5%, VDD = 18V \pm 0.5V
- 2. Each pin except VDD and GND will have a series resistor of 47K \pm 5%; Group E, Subgroup 2, sample size is 4 dice/wafer, 0 failures, VDD = 10V \pm 0.5V

TABLE 9. DATA TRANSFER TABLE*

INITIAL STATE			CLOCK	RESULTING STATE	
DATA INPUT	CLOCK INHIBIT	INTERNAL STAGE	LEVEL CHANGE	INTERNAL STAGE Q	OUTPUT
0	0	Х	\	0	NC
Х	0	0	/	NC	0
1	0	Х	\	1	NC
Х	0	1	_	NC	1
Х	1	1	Х	NC	NC

0 = Low Level 1 = High Level X = Don't Care NC = No Change

Data Input = SHIFT RIGHT INPUT (Term. 11)

Internal Stage = Stage 1 (Q1)

Output = SHIFT LEFT OUTPUT (Term. 4)

For Shift Left Mode

Data Input = SHIFT LEFT INPUT (Term. 6)

Internal Stage = Stage 32 (Q32)

Output = SHIFT RIGHT OUTPUT (Term. 12)

TABLE 10. CONTROL TRUTH TABLE

LEFT/RIGHT CONTROL	CLOCK INHIBIT	RECIRCULATE CONTROL	ACTION	INPUT BIT ORIGIN
1	0	1	Shift Left	Shift Left Input
1	0	0	Shift Left	Stage 1
0	0	1	Shift Right	Shift Right Input
0	0	0	Shift Right	Stage 32
Х	1	Х	No Shift	-

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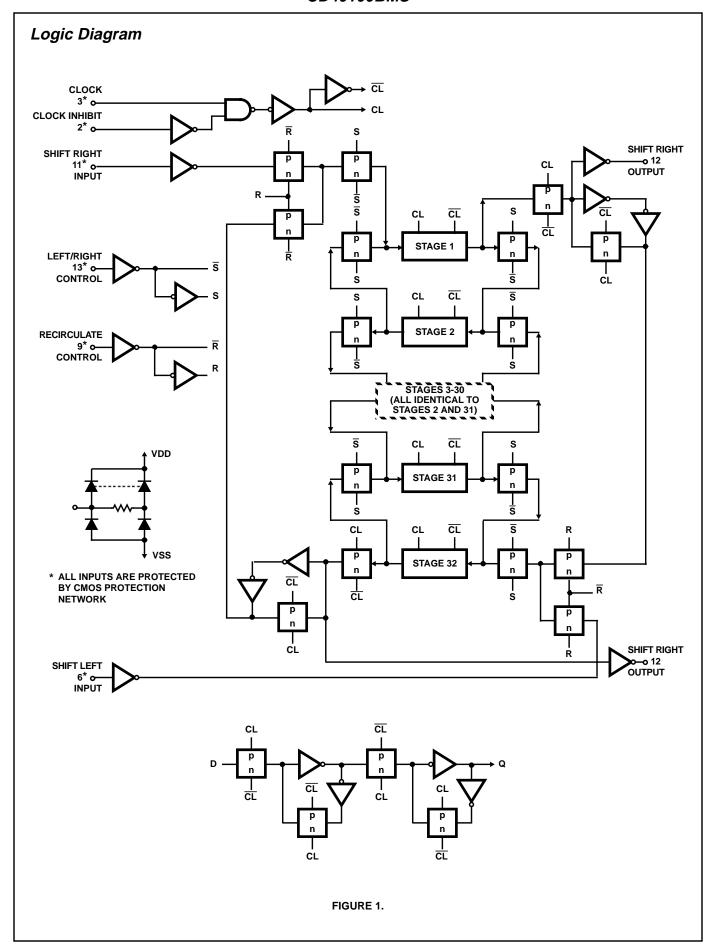
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^{*} For Shift-Right Mode



Typical Performance Characteristics

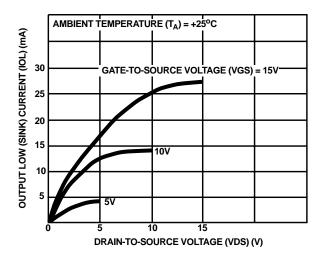


FIGURE 2. TYPICAL OUTPUT LOW (SINK) CURRENT CHARACTERISTICS

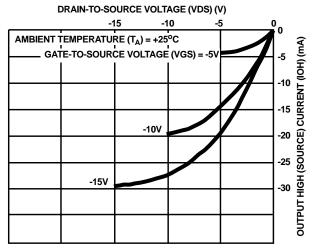


FIGURE 4. TYPICAL OUTPUT HIGH (SOURCE) CURRENT CHARACTERISTICS

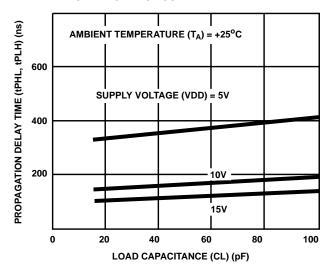


FIGURE 6. TYPICAL PROPAGATION DELAY TIME (CLOCK TO SHIFT LEFT/RIGHT) AS A FUNCTION OF LOAD CAPACITANCE

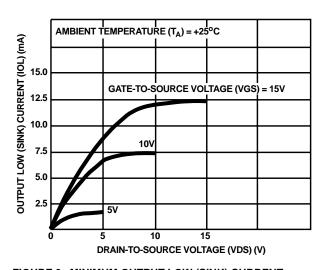


FIGURE 3. MINIMUM OUTPUT LOW (SINK) CURRENT CHARACTERISTICS

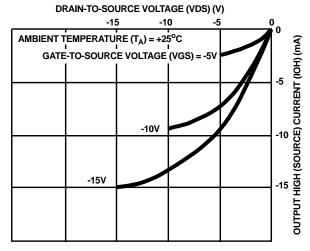


FIGURE 5. MINIMUM OUTPUT HIGH (SOURCE) CURRENT CHARACTERISTICS

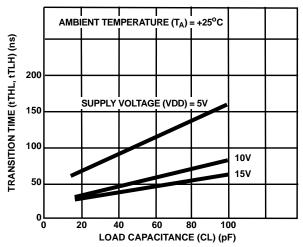


FIGURE 7. TYPICAL TRANSITION TIME AS A FUNCTION OF LOAD CAPACITANCE

Typical Performance Characteristics (Continued)

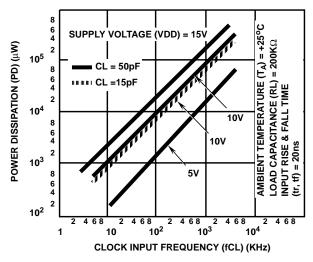


FIGURE 8. TYPICAL DYNAMIC POWER DISSIPATION AS A FUNCTION OF CLOCK FREQUENCY

Timing Diagram

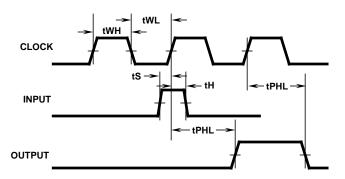
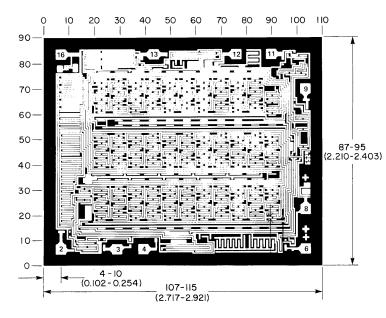


FIGURE 9. TIMING DIAGRAM DEFINING SETUP, HOLD, AND PROPAGATION DELAY TIMES

Chip Dimensions and Pad Layout



Dimensions in parenthesis are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10⁻³ inch).

METALLIZATION: Thickness: 11kÅ – 14kÅ, AL. PASSIVATION: 10.4kÅ - 15.6kÅ, Silane BOND PADS: 0.004 inches X 0.004 inches MIN DIE THICKNESS: 0.0198 inches - 0.0218 inches